506243000 09/09/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6289744

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
GAKUHITO HIRASAWA	08/03/2020
TAKASHI TSUNAKAWA	08/25/2020
DAISAKU YAMATO	08/25/2020

RECEIVING PARTY DATA

Name:	NATIONAL UNIVERSITY CORPORATION CHIBA UNIVERSITY		
Street Address:	1-33, YAYOI-CHO, INAGE-KU, CHIBA		
City: CHIBA-SHI			
State/Country: JAPAN			
Postal Code:	2638522		
Name: MAEDA CORPORATION			
Street Address:	10-2, FUJIMI 2-CHOME, CHIYODA-KU		
City:	TOKYO		
State/Country:	JAPAN		
Postal Code:	1028151		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16979332

CORRESPONDENCE DATA

Fax Number: (703)726-6024

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: ROSSI, KIMMS & MCDOWELL LLP Address Line 1: 20609 GORDON PARK SQUARE

Address Line 2: SUITE 150

Address Line 4: ASHBURN, VIRGINIA 20147

ATTORNEY DOCKET NUMBER: SEIS-0036US1

NAME OF SUBMITTER: TAMMY KASSICK

PATENT 506243000 REEL: 053723 FRAME: 0676

SIGNATURE:	/Tammy Kassick/		
DATE SIGNED:	09/09/2020		
Total Attachments: 6			
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PATENT REEL: 053723 FRAME: 0677

Attorney Docket No. SEIS-0036US1 Assignee Ref. No.

ASSIGNMENT

United States Patent Rights, or United States Plus all Foreign Patent Rights

Application No.: 16/979,332	Filed:	September 9, 2020
WHEREAS,		
(hereinafter designated as the undersigned Title: WOOD PROCESSING SYSTEM	ed) has (have) invented certain ne	ew and useful improvements in:
for which an application for Letters Paten	t of the United States of America	has been executed by the undersigned.
WHEREAS, NATIONAL UNIVERSITY O	CORPORATION CHIBA UNIVERS	ITY and MAEDA CORPORATION
respectively, its heirs, successors, legal representative	es and assigns (hereinafter desig	2-chome, Chiyoda-ku, Tokyo, 1028151 JAPAN, nated as the Assignee) is desirous of acquiring Letters Patent(s) that may be granted therefor in
in any foreign countries.		
assigned and transferred, and by these pr right to the said invention in the United Statitle and interest in and to any and all Let territories, dependencies and possession	esents does (do) sell, assign and t ates of America, its territories, dep tters Patent(s) which may be gran is, and if the box above is designa	knowledged, the undersigned has (have) sold, ransfer unto said Assignee the full and exclusive endencies and possessions and the entire right, ted therefor in the United States of America, its ted, in any and all foreign countries; and to any eof for the full term or terms for which the same
The undersigned agree(s) to execute all p conversion or reissue applications thereo as the Assignee may deem necessary or	of and also to execute separate as	th this application and any continuing, divisional, ssignments in connection with such applications
which may be declared concerning this	application or continuation, division and to cooperate with the As	with any interference or post-grant proceeding sion, conversion or reissue thereof or Letters signee in every way possible in obtaining and
		perform any act which may be necessary in the Protection of Industrial Property or similar

SINGLE ASSIGNEE

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) or a grant of (a) valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

Attorney Docket No. SEIS-0036US1

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Rossi, Kimms & McDowell LLP the power to insert on this Assignment any identification, including but not limited to the Attorney Docket Number, or make corrections thereto, which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date	Aug. 3, 2020	Name of Inventor	(Signature) Gakuhito HIRASAWA
Date		Name of Inventor	(Signature) Takashi TSUNAKAWA
Date		Name of Inventor	(Signature) Daisaku YAMATO
Date		Name of Inventor	(Signature)
Date		Name of Inventor	(Signature)
Date		Name of Inventor	(Signature)

Attorney Docket No. SEIS-0036US1 Assignee Ref. No.

ASSIGNMENT

United States Patent Rights, or United States Plus all Foreign Patent Rights

Application No.: 16/979,332 Filed: September 9, 2020
WHEREAS.
(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in: Title: WOOD PROCESSING SYSTEM
for which an application for Letters Patent of the United States of America has been executed by the undersigned.
WHEREAS, NATIONAL UNIVERSITY CORPORATION CHIBA UNIVERSITY and MAEDA CORPORATION
of, 1-33, Yayol-cho, Inage-ku, Chiba-shi, Chiba 2638522 JAPAN; and 10-2, Fujimi 2-chome, Chiyoda-ku, Tokyo, 1028151 JAPAN, respectively, its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and
in any foreign countries.
For good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these presents does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.
The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.
The undersigned agree(s) to execute all papers necessary in connection with any interference or post-grant proceeding which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and for such proceeding.
The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) or a grant of (a) valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

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Attorney Docket No. SEIS-0036US1

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The undersigned hereby grant(s) the law firm of Rossi, Kimms & McDowell LLP the power to insert on this Assignment any identification, including but not limited to the Atlorney Docket Number, or make corrections thereto, which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

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In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date		Name of Inventor	
			(Signature) Gakuhito HIRASAWA
Date	August 25, 2020	Name of Inventor	Jakashi Jsunakawa (Signalure) Takashi TSUNAKAWA
			(Signature) Takashi TSUNAKAWA
Date		Name of Inventor	
			(Signature) Daisaku YAMATO
Date		Name of Inventor	
			(Signature)
Dale		Name of Inventor	
			(Signature)
Date		Name of Inventor	
		a american, mar feral comprises.	(Signature)

Attorney Docket No. SEIS-0036US1 Assignee Ref. No.

ASSIGNMENT

United States Patent Rights, or United States Plus all Foreign Patent Rights

Application No.: 16/979,332	Filed: September 9, 2020
WHEREAS,	
(hereinafter designated as the undersigned) has (have) Title: WOOD PROCESSING SYSTEM	invented certain new and useful improvements in:
for which an application for Letters Patent of the United	States of America has been executed by the undersigned.
WHEREAS, NATIONAL UNIVERSITY CORPORATION	N CHIBA UNIVERSITY and MAEDA CORPORATION
respectively, its heirs, successors, legal representatives and assigns	AN; and 10-2, Fujimi 2-chome, Chiyoda-ku, Tokyo, 1028151 JAPAN, (hereinafter designated as the Assignee) is desirous of acquiring and in and to any Letters Patent(s) that may be granted therefor in
in any foreign countries.	
assigned and transferred, and by these presents does (doinght to the said invention in the United States of America title and interest in and to any and all Letters Patent(s) territories, dependencies and possessions, and if the bo	thich is hereby acknowledged, the undersigned has (have) sold, o) sell, assign and transfer unto said Assignee the full and exclusive it, its territories, dependencies and possessions and the entire right, which may be granted therefor in the United States of America, its exabove is designated, in any and all foreign countries; and to any and extensions thereof for the full term or terms for which the same
	ry in connection with this application and any continuing, divisional, xecute separate assignments in connection with such applications
which may be declared concerning this application or	sary in connection with any interference or post-grant proceeding continuation, division, conversion or reissue thereof or Letters perate with the Assignee in every way possible in obtaining and
	documents and to perform any act which may be necessary in al Convention for the Protection of Industrial Property or similar
of America patent(s) or a grant of (a) valid United States	which may be necessary to obtain a grant of (a) valid United States s of America and any foreign patent(s) to the Assignee and to vest as fully and entirely as the same would have been held by the lade.

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SINGLE ASSIGNEE

Attorney Docket No. SEIS-0036US1

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

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In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date		Name of Inventor	(Signature) Gakuhito HIRASAWA	
Date		Name of Inventor		
Date	August 25, 2020	Name of Inventor	(Signature) Takashi TSUNAKAWA Arianka Jamako	
	- Company Comp		(Signature) Daisaku YAMATO	
Date	3	Name of Inventor		
			(Signature)	
Date		Name of Inventor	-	*
			(Signature)	
Date		Name of Inventor	(Signature)	

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